	COUNT	DESCRIPTION OF	F REVI	SIONS	BY	CHKD	DATE		COUN	т [DESCR	IPTION OF RE	VISIONS	BY	CHK) D/	ATE
Δ								À								—	
<u> </u>	1 10 4							Δ									
API	PLICA	BLE STANDARI	ט	I						C+~"	10.00		1				
RATING		Operating Temperature Range								torage -10°C to +60°C			-60°C	C(Note3)			
		Operating Humic						Stor	corage Humidity 40% to 70% (N			lote3)	ote3)				
		Range							Rang	inge 40% to 70%			7070 (1	(11000)			
		Applicable Conr								_		AWG 30 : 0.5A AWG 28 : 1.0A				1.0A	
		Voltage							Curr			AWG 26 : 1.5A AWG 22-24 : 2.0A					
		Voicago	SPECIFICATION														
			T					FIC	AHC	<u> NS</u>	<u> </u>						
		ITEM			TES	ST ME	THOD					REQUIR	EMENT	<u>s</u>		<u> QT</u>	AT
		UCTION	\ <i>r</i> 1													Τ.	
Mark	eral Exar	mination	_	med vis		uring in	strument			— A	ccordin	g to drawing.				0	0
		CAL CHARAC														<u>т </u>	
	tact Res					or 100	10H2)			3(n mo M	1 A Y				$\overline{}$	
		el Method	20mV MAX, 1mA (DC or 1000Hz).							0	30 mΩ MAX.				0	-	
Insulation Resistance			500 V DC.							1,	1,000 MΩ MIN.				+-		
											,				0	_	
Voltage Proof			650 V AC for 1 min.							N	No flashover or breakdown.				0	_	
		ICAL CHARA															
Mec	hanical (Operation	30 times insertion and extraction.							①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts. ①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts.							
		(Sn Plating)												(2	0	_	
Mecl	hanical (Operation	50 times insertion and extraction.						(1					+			
IVICOI	namear ((Au Plating)												0	_		
		(, ,g,										3 /		•			
Mati	ng and u	ınmating	It takes out and inserts with a conformity connector.						or. (1]]Inserti	on Force: 72.2N	I MAX					
force (Sn Plating)									2	②Extraction Force: 4.2N MIN				0	-		
			<u>.</u>							-		- 40.01				┿	
		inmating (Au Plating)	It takes out and inserts with a conformity connector.							②Extraction Force: 46.2N MAX				0			
force	e	(Au Plating)								۷	<u>∠</u> /⊑xtrac	cuon Force. 4.01	A IAITIA			1 "	
Vibra	ation		Freque	ency 10	to 55 I	Iz, sing	le ampliti	ıde 0.	.75 mm	, (1	No ele	ctrical disconti	nuity of 1	μs.		+-	
			Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.								②No damage, crack or looseness of parts.				0	_	
Shock			Acceleration 490 m/s ² duration of pulse 11 ms at 3							t 3							
			times for 3 directions.												0	-	
	//DO	IMENITAL OLL	1040	TEDI													
		IMENTAL CHA					00	. 05	0/ 00 1	G	<u> </u>		00 0 144				
Damp Heat (Steady State)			Exposed at 40 ± 2 °C, humidity 90 to 95 %, 96 h.								①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 500MΩ MIN.				0	_	
			(After leaving the room temperature for 1 to 2h.)							③No damage, crack or looseness of parts.							
Rem	arks									0	y						ı
		de the temperature	rising	by curr	ent.												
		ondensing y to the condition o	of long t	term sto	orage fo	or unuse	ed produc	cts be	fore p	cb on	board,	after pcb board	l, operatir	ng temp	erature	e and	
	hum	idity range is applie	d for in	iterim st	torage	during t	ransporta	ation.									
								DRAW	/N	DE	ESIGNEI	D CHECKE	D AF	PROVE	D	RELEA	SED
					J	J.S CHO		J.S CHO		O S.M.LIM S.M.LIM		<i></i>	ENG 2022.12.05				
						,	21.04.28		21.04.28		21 04 3	21.04.28 21		04 00 -		/	
Unles	ss otherw	vise specified, refer t	to IEC 60512.			'	21.07.20			21.04.2		21.07.20			DEP	ソ	
NOT		QUALIFICATION			SURA	NCE TE	ST O: A	PPLI	CABL	E TES	ST	1	1				
												PART NO.					
HIROSE KOREA CO.,LTD.			D. SPECIFICATION SHEET			<u> </u>	DF51K-16DP-2V(8			(800)						
CODE NO.(OLD)			DRAWING NO.					CODE NO.				CI 6	6652-0077-3-800				1/
CL					ELC	ELC4-633523						0_0	OL 0002-0011-3-000 / 9				

Temperature −55 °C → +105 °C	①Contact resistance: 30 mΩ MAX.				
Time 30min → 30min	②Insulation resistance: 1,000M Ω MIN.	0	-		
Under 5 Cycles.	③No damage, crack or looseness of parts.				
(The transferring time of the tank is 2 to 3 MIN)					
(After leaving the room temperature for 1 to 2h.)					
Exposed at 105±2 °C, 96h	①Contact resistance: 30 mΩ MAX.				
	②Insulation resistance: 1,000M Ω MIN.	0	-		
	③No damage, crack or looseness of parts.				
Exposed at -55±3 °C, 96h	①Contact resistance: 30 mΩ MAX.				
	②Insulation resistance: 1,000M Ω MIN.	0	-		
	③No damage, crack or looseness of parts.				
Reflow time	No deformation of case of excessive looseness	\top	\vdash		
Number of reflow cycles : 2cycles MAX	of the terminals.				
Peak temperature : 250°C 10sec. MAX		0 -			
Soldering temperature: 245 °C	New uniform coating of solder shall cover	+	†		
Duration of immersion :soldering, for 5 sec.	minimum of 95 % of the surface Being	0	-		
	immersed.				
DESCRIPTION TEMPERATURE PROFILE LIGHT LEAD EDGE COLDED DASTE	(DECEDENCE)				
REFLUW TEMPERATURE PRUFILE USING LEAU-FREE SULUER PASTE	(REFERENCE)				
†(℃) 10s MAX					
250 NUM	IBER OF REFLOW CYCLES 2CYCLES MAX.				
	TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.				
180					
150					
90~120s PCB					
100 /	·				
/ MUL	NTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.				
[
(S)					
	Time 30min → 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.) Exposed at 105±2 °C, 96h Exposed at −55±3 °C, 96h Reflow time Number of reflow cycles: 2cycles MAX Duration above 220°C, 60sec. MAX. Peak temperature: 250°C 10sec. MAX Soldering temperature: 245 °C Duration of immersion: soldering, for 5 sec. REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE 100 100 100 100 100 100 100 1	Time 30min → 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.) Exposed at 105±2 °C, 96h Exposed at 105±2 °C, 96h ①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts. □Contact resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts. □Contact resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts. No deformation of case of excessive looseness of the terminals. Reflow time Number of reflow cycles: 2cycles MAX Duration above 220°C, 60sec. MAX. Peak temperature: 250°C 10sec. MAX Soldering temperature: 245 °C Duration of immersion: soldering, for 5 sec. New uniform coating of solder shall cover minimum of 95 % of the surface Being immersed. REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE) 100 MAX ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE. PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILES. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.	Time 30min → 30min 20Insulation resistance: 1,000MΩ MIN. 0 Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.) Exposed at 105±2 °C, 96h D'Contact resistance: 30 mΩ MAX. 2 Insulation resistance: 1,000MΩ MIN. 3 No damage, crack or looseness of parts. Exposed at -55±3 °C, 96h D'Contact resistance: 30 mΩ MAX. 2 Insulation resistance: 1,000MΩ MIN. 3 No damage, crack or looseness of parts. Reflow time Number of reflow cycles: 2 cycles MAX Duration above 220°C, 60sec. MAX. Peak temperature: 245 °C Duration of immersion: soldering, for 5 sec. New uniform coating of solder shall cover minimum of 95 % of the surface Being immersed. REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE) 100 REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE) 100 NUMBER OF REFLOW CYCLES 2CYCLES MAX. THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART. THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART. THE PROFILES. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.		

NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST O: APPLICABLE TEST									
HIROSE KOREA CO.,LTD		SPECIFICATION	LOUEET	PART NO.					
HIROSE KOREA GO.,LTD	'·	SPECIFICATION	SHEET	DF51K-16DP-2V(800)					
CODE NO.(OLD)	DRAWING	NO.	CODE NO.	CL 6652-0077-3-800	2/				
CL		ELC4-633523		OL 0032 0077 3 800	/ 2				